

## Briefing to the ESSAAC Technology Subcommittee (TSC)

on

## Radar Electronics Technology Requirements & Roadmaps

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ESTO



## Introduction

- · Process to Derive Technology Requirements
- Measurement Types
- · Technology Needs
- Example Requirements & Roadmaps: Large Aperture L-band SAR
- Integrated Radar Roadmap
- · Concluding remarks

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## Process to Derive Radar Technology Requirements

- ESTO formed a Radar/Radiometer Working Group whose charter is to validate the ESTIPS database and then generate technology roadmaps and development plans
- Members of the working group include JPL, GSFC, university and industry participation
- · 42 radar measurement scenarios were reviewed
  - Measurement scenarios/parameters were mapped to science roadmap
  - Technology challenges were assessed
    - · Performance or environmental requirements
    - · Resource constraints (mass, power, cost)
    - · Technology survey
  - Scenarios were classified
    - Enabling, Enhancing, Mature, Obsolete
  - Prioritized technology needs
    - · Focus on technologies enabling multiple high-priority measurements



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## Measurement Types

Measurement Type	Criticality	Utility (scenario ID)		
Large aperture SAR	Enabling	MEO/GEO L-band InSAR (45, 46) UHF/VHF Deep Soil Moisture (112)		
X-, Ku- & Ka-band Single-Pass Interferometers (using phased array antennas)	Enabling	100, 28?, 93, 161A, 163		
Millimeter Wave Atmospheric Radars using phased array antennas (Ka-, Wband, G-band)	Enabling	75, 76, 159, 160		
Moderate aperture SAR	Enhancing	22, 105, 92, 19, 44a, 44b, C1, 97, 158, 162		
Millimeter Wave Atmospheric Radars (Ka-, W-band)	Enhancing	68, 142, 154		
MEO Scatterometer	Enhancing	148		
Misc.	Enhancing	O2, 30, 51		
Airborne/Suborbital Platforms	Enhancing	161B, 161C, 47, 157		
Mature measurement scenarios	Mature technology	102, 151, 155, 29, 61, 90, 156		
Obsolete measurement scenarios	Obsolete	103, 104		

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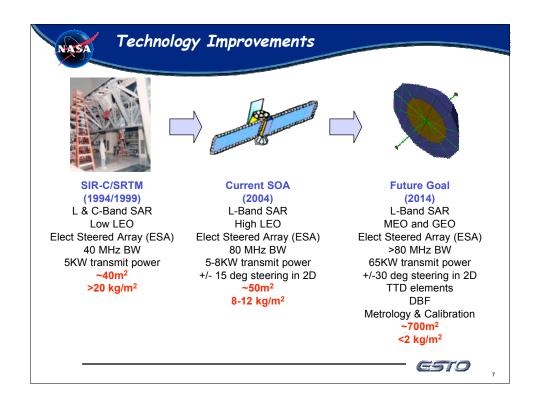


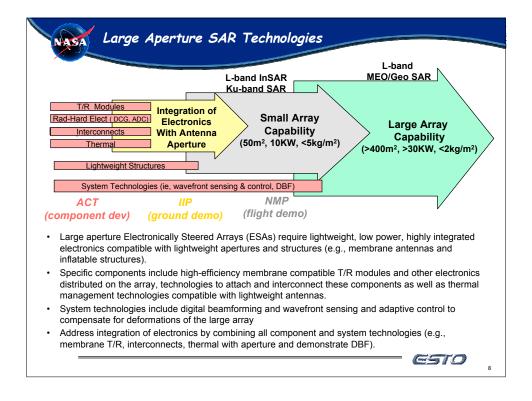
### Primary areas recommended for technology investment:

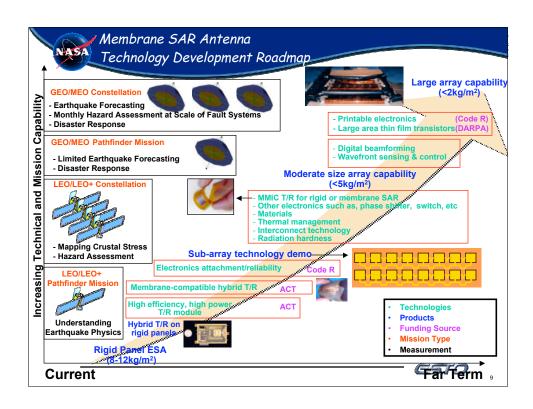
- 1. Large Aperture SAR technologies
  - Focuses on electronics required for lightweight ESA (particularly L-band and Ku-band)
  - Will also benefit near-term SAR missions (of moderate aperture size)
- 2. X, Ku, Ka-band Interferometers
  - · Focuses on developing electronics for phase-stable ESA
  - · X-band is lower priority since significant investment by DoD
- 3. Millimeter Wave Atmospheric Radar
  - · Focuses on millimeter wave ESA (Ka, W, G-band)

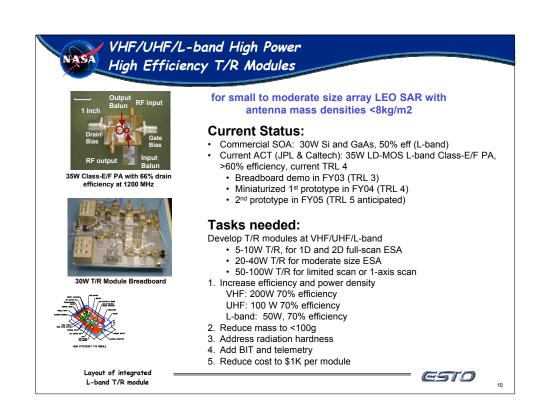


Technology Challenges NASA **Higher Orbits** Lower Frequency (MEO, GEO) Large Deployable (UHF, P-band) (L-, Ku-, Ka-band) **Antennas** Electronics System Large Deployable Antenna Structures **Aperture** - Frequency/BW - Tx Power - Wide-area imaging - Resolution - Frequency/BW - Stiffness - Phase stability improvement - Surface flatness Scanning - Low DC power Enhanced - Lightweight Multiple beams - Low mass measurement - Lightweight materials - Stowed volume - Low cost - Rad-Hard - Cost reduction Metrology/Calibration **Phased Array** T/R modules - Inflatables Wavefront sensing and Phased-Array Feed **MMIC** devices - Deployables - Interferometric Reflect-array High pwr transmitters **Digital beamforming** Large Reflector Chirp generators
Digital receivers masts (>100m) - Manufacturability Large Rotating Reflector Multiple-feeds or shared-Thermal mgmt aperture - Signal distribution **E510** 







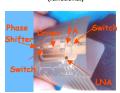




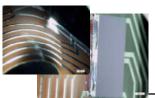
### Membrane L-band T/R Modules



ACT: Flex T/R using packaged parts



ACT: T/R using flip chip attachment (non functional prototype for flip chip development)



ACT: Test die flip chip attachment reliability testing

#### for large array MEO/Geo SAR with antenna mass densities <2kg/m2

### **Current Status:**

- Commercial SOA: does not exist
   Current ACT: 1W T/R using GaAs packaged parts, TRL 2
  - 1st Prototype demo (T/R only) in FY04
  - 2<sup>nd</sup> Prototype (T/R+controls) in FY05 (TRL 3 anticipated)

#### Tasks needed:

Develop membrane compatible T/R modules including attachment/packaging techniques and manufacturing techniques for low costs and high reliability

- 1. Optimize circuit design for membrane T/R
- 2. Improve T/R packaging and/or attachment
  - a- die inside a low profile package
  - b- direct attachment of die (i.e. flip chip)
- 3. Address radiation (through packaging) (>1MRad)
- 4. Increase transmit power (to 5-10W)
- 5. Increase efficiency (s.a. incorporating High-Eff PA)
- 6. Address thermal management
- 7. Address manufacturability, reliability
- 8. Add BIT and telemetry
- 9. Reduce cost <\$500 per module

NOTE: Tasks 1-9 are not yet funded



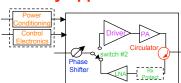
#### Single-Chip MMIC L-band NASA T/R Modules

## for moderate to large SAR array applications

## **Current Status:**

Most T/R modules consist of multiple (5-6) MMICs plus discrete passives in a hybrid microcircuit. Cost is typically \$1-5K in large quantities. Limited work is being done commercially to develop single chip L-band T/R modules. RF functions are being integrated into a single chip but some key components remain off-chip (circulators, control & power). Work is being done in CMOS for integrating the controls and GaAs for integrating the RF.





T/R module

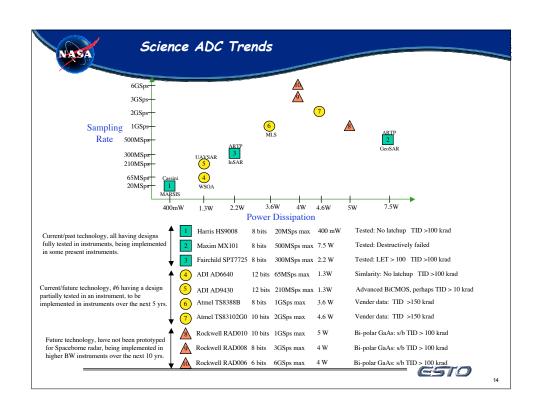
#### Tasks needed:

Develop a fully integrated MMIC T/R module:

- 1. Develop individual RF components (PA, LNA, P/S, switches) using a rad-hard semiconductor process (e.g., GaAs, SOI CMOS, SiGe).
- 2. Develop digital control components, BIT and telemetry
- 3. Integrate into a single MMIC chip.
- 4. Improve RF performance (inc power, efficiency, reduce NF)
- 5. Address radiation hardness (with minimal shielding)



## Waveform Generators applicable to nearly all radar applications **Current Status:** STEL-2375B GaAs NCO, 400 MHz max BW, 40 dB SFDR, 15W DC. Currently at TRL 6. Prototype built and tested, airborne validated. OSTM/WSOA will raise TRL from 6 to 9 by 2008. AD-9858, CMOS NCO, 325 MHz max BW, 3W DC, no radiation test data STEL-2375B high-speed GaAs available. Currently at TRL 4. In process of prototyping and radiation NCO-based DCG Tasks Needed: Direct-Digital-Synthesizer Technology Trends Develop low power, high-speed (>300MHz BW), rad-hard (1MRad) integrated chirp generators · Reduce power consumption <5W by 2006, <2W by 2008, <1W by 2012 · Increase speed (bandwidth) and SFDR (low • Reduce mass (eg., single chip ASIC) · Increase flexibility (arbitrary waveform Increase radiation hardness (particularly for 15 2 Years to market MEO, Geo applications) *ESTO*





## High-Speed Science ADC

#### **Current Assessment**

- ADC trends indicate most Code Y missions will have suitable ADC devices available EXCEPT
  - MEO and GEO applications requiring radiation hardening
  - MEO or GEO SAR requiring very low DC power for distributed array architectures
  - Most SAR applications would benefit from higher dynamic range (# bits)

#### **Future Technology Development Tasks**

Development of rad-hard, low power, high-speed, >8-bit ADCs.

- 1. Reduced power consumption for large array applications (<0.5W)
- 2. Radiation hardening for MEO/Geo:

100kRad (by 2006)

500 KRad (by 2010)

1MRad (by 2014)

 Increased dynamic range: Increase the number of bits (from 8-bit to 12-bit) for moderately high-speed ADC (300MHz)



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## Signal Distribution & Interconnect







Current SOA: Cable Bundles

#### **Current Status:**

Large cable bundles distribute RF, power and control signals. These heavy cables are not compatible with ultra-lightweight antennas (i.e.-membrane). They are also expensive requiring extensive manual labor to build and integrate.

#### Tasks needed:

Development of technologies to simplify the interconnection of thousands of unit cells of ESA; significantly reduce mass and volume; develop reliable RF, control, power, and data distribution.

#### Sample Candidate Technologies:

1- Printed interconnects:

Challenges: Amount of current on printed lines, providing redundancy

#### 2- Wireless interconnects:

Challenges: Bandwidth to support the amount of data, Possible RF interference

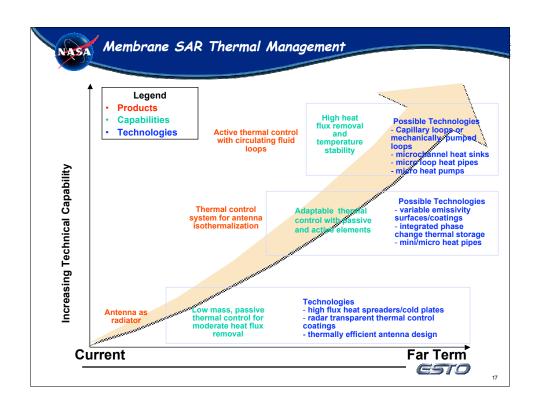
#### 3- Optical interconnects:

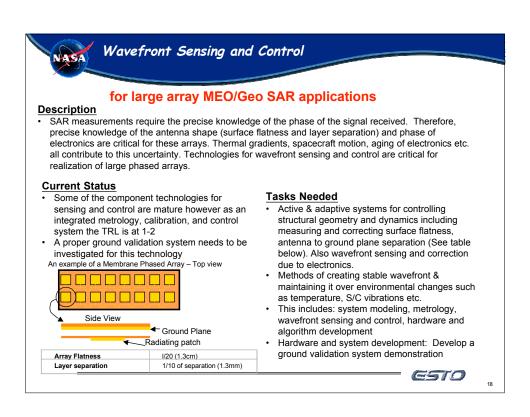
Challenges: Large mass and power consumption of optical components, reliability

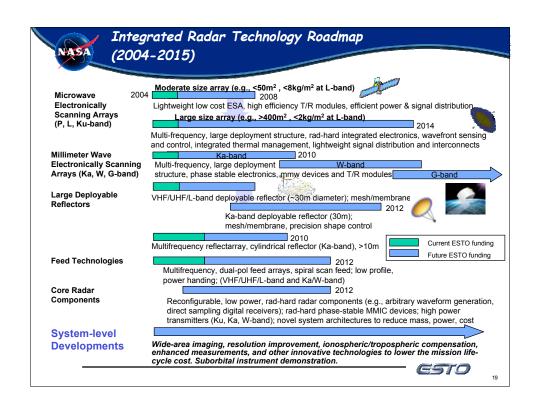
#### 4- Signal multiplexing:

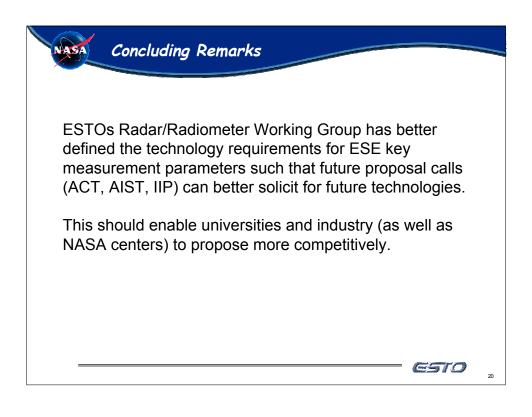
Challenges: system complexity, interference/isolation













# BACK-UP SLIDES

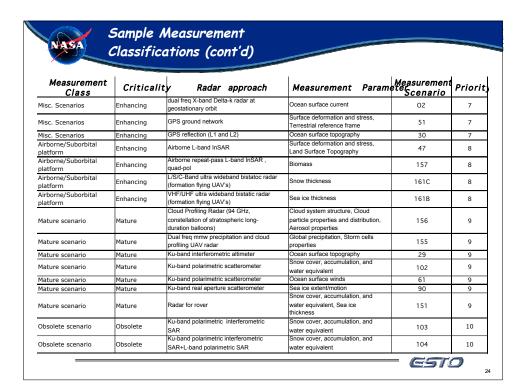


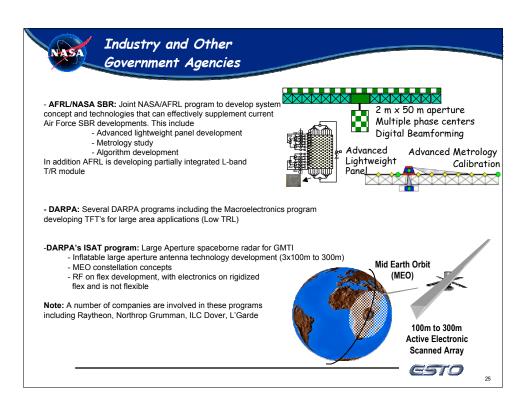
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Measurement Class	Criticalit	y Radar approach	Measurement Param	Measurement eter Scenario
arge Aperture SAR	Enabling	Constellation of L-band geosynchronous InSAR	Surface deformation and stress, Land Surface Topography	46
arge Aperture SAR	Enabling	MEO L-band InSAR	Surface deformation and stress, Land Surface Topography	45
Large Aperture SAR	Enabling	UHF/VHF polarimetric SAR	Soil moisture (deep)	112
Single-Pass Interferometer using phased-array	Enabling	Ka-band along/across track interferometric SAR	River stage height, River discharge rate	100
Single-Pass Interferometer using phased-array	Enabling	Ka-band synthetic aperture altimeter	Ocean surface topography	28
Single-Pass Interferometer using phased-array	Enabling	Ku-band single pass interferometric SAR	Ice surface topography	93
Single-Pass Interferometer using phased-array	Enabling	VHF/Ku-band space and frequency domain interferometic bistatic radar	Sea ice thickness	161A
Single-Pass Interferometer using phased-array	Enabling	X-band single pass InSAR	Land Surface Topography	163
Millimeter Wave Atmospheric Radar using Phased-Array	Enabling	14/35/94GHz Precipitation Radar	Global precipitation	76
Millimeter Wave Atmospheric Radar using Phased-Array	Enabling	14/35GHz Precipitation Radar	Global precipitation	75
Millimeter Wave Atmospheric Radar using Phased-Array	Enabling	35GHz Doppler rain profiling radar	Global precipitation, Storm cells properties	160
Millimeter Wave Atmospheric Radar using Phas <u>ed-Array</u>	Enabling	94/140GHz scanning cloud profiling radar	Cloud system structure, Cloud particle properties and distribution	159



Measurement Class	Criticalit	y Radar approach	Measurement Param	Measurement eter Scenario	Priorit
Moderate Aperture SAR	Enhancing	Ka-band single pass interferometric SAR	Sea ice thickness	97	4
Moderate Aperture SAR	Enhancing	Ku/L-band Polarimetric SAR	Snow cover, accumulation, and water equivalent	105	4
Moderate Aperture SAR	Enhancing	L-band dual polarization SAR	Freeze-thaw	22	4
Moderate Aperture SAR	Enhancing	L-band polarimetric SAR	Land cover and land use	162	4
Moderate Aperture SAR	Enhancing	L-band Repeat-Pass Interferometric SAR	Polar ice sheet/glacier velocity	92	4
Moderate Aperture SAR	Enhancing	LEO L-band InSAR	Surface deformation and stress	44a	4
Moderate Aperture SAR	Enhancing	LEO repeat-pass interferometric L-band SAR, quad polarization	Biomass	158	4
Moderate Aperture SAR	Enhancing	P-band polarimetric SAR	Biomass	19	4
Moderate Aperture SAR	Enhancing	Two formation flying LEO L-band SAR	Land Surface Topography	44b	4
Moderate Aperture SAR	Enhancing	Wide-swath Sea Ice Motion C-Band SAR	Sea ice motion and deformation	C1	4
Millimeter Wave Atmospheric Radar	Enhancing	35GHz Differential Frequency Precipitation Radar	Global precipitation	154	5
Millimeter Wave Atmospheric Radar	Enhancing	94GHz Cloud Profiling Radar	Cloud system structure, Cloud particle properties and distribution	142	5
Millimeter Wave Atmospheric Radar	Enhancing	Atmospheric occultation	Atmospheric water vapor, Ozone vertical profile	68	5
MEO Scatterometer	Enhancing	Ku-band polarimetric scatterometer at MEO	Ocean surface winds	148	6







# NASA Academic and Industry

# Representative listing of academic and industry participation/collaborations

- Radar Remote Sensing:
- Univ. of Michigan, UMass, University of Kansas
- Antennas:
- UCLA, UMass
- Lockheed, Raytheon, NGST, Ball, Harris, ILC Dover, L'Garde, Astro Aerospace, AEC Able, Composite Optics
- High Efficiency Power Devices and Amplifiers:
- Caltech, Univ. of Iowa
- CREE (SiC, GaN), CPI, Thales
- RF IC's, MMIC's, MEMS:
- University of Michigan, Arizona State University, Kansas State University, Caltech, UCLA
- Honeywell, Peregrine, Rockwell, Remec, U.S. Monolithics, NGST, Raytheon
- Packaging/Materials:
- Auburn University, Georgia Tech., Penn State





## for large array MEO/Geo SAR applications

#### **Current Status**

· Hardware: Mixed-signal (ADC) and reconfigurable (FPGA) IC technology at TRI 4-5

Firmware: Algorithm development at TRL 3.

• Proof-of-concept demonstrated: STAR radiometry, SBR, next-generation DSN array (TRL 3-5).

#### **Tasks Needed**

Build a hardware prototype of multi-channel L-band DBF system:

- 1. Rad-hard, low power, high-speed A/D conversion applied near antenna subsystem (at panel or element level).
- 2. Distributed microwave coaxial cables replaced with phase-stable digital fiber-optic network.
- 3. Address SEU immunity using "Rad-Hard by design" techniques

### Instrument/Platform Requirements

- Large antenna: 20-50 m antenna span (rectangular panel array or circular aperture).
- Direct RF A/D conversion: 1.26 GHz carrier
- frequency, 80 MHz bandwidth, 8-12 bit resolution.
- · High data throughput: Electronic beam steering, combining >30 phase center channels.
- Phase stability: 10–100 millidegree phase precision over wide thermal gradients.
- On-board processing rate: 10-100 billion op/s.



concept



High-speed GaAs

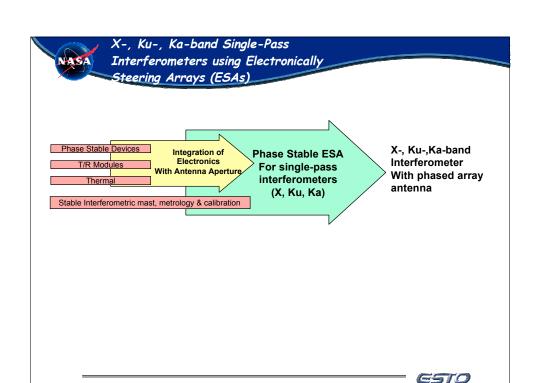
and SiGe ADCs (up to 6 GHz input bandwidth)



High density FPGAs (up to 8 million gates)



Technology path toward single-chip receivers for a SAR array.

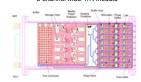




#### Ka-band T/R Modules

## similar roadmap for Ku-band or X-band

#### Layout of Receive side of 8-channel MSL T/R module



Photograph of receive side of 8-channel MSL T/R module



#### **Current Status:**

- 1 W transmit chain, 20% efficiency demonstrated (using Triquint 2W chip) (TRL 3)
- · 8-channel LTCC module w/ GaAs MMICs
  - 17 dBm output power, 4GHz BW
  - · Low power-added efficiency (low power module)
  - · 30 g/channel mass
- · Developed under ATIP and Mars Focused Tech Program
  - Multi-module brassboard demonstrated circuitry (TRL 4)
- · There are no equivalent commercial products

#### Tasks needed:

- 1. Improvement in efficiency to 30% (by 2006) to 50% (by 2010)
- 2. Increase power to 3W (by 2006) to 10W (by 2010) (Triquint 6W MMIC chip recently available)
- 3. Address phase stable receive electronics (for interferometers)
- Further miniaturization and application specific packaging (ie, 2D array)
- 5. Reduced mass and cost
- 6. Add BIT and telemetry



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## W-band & G-band Devices for T/R modules

## MMIC development at 95GHz and 140GHz

#### **Current Status:**

- W-band (95 GHz) components:
  - 0.25W PA, 6dB NF LNA
- · G-band (140 GHz) components:
  - · T/R components (particularly PA) do not exist

### Tasks needed:

Basic research to develop new MMIC devices using GaAs, GaN, InP, MEMS (or other emerging semiconductor technologies) at 95 GHz and 140 GHz for future T/R modules

- Develop MMIC devices such as power amplifiers (PAs), LNAs, Phase Shifters, switches, filters. Performance goals:
  - W-band MMICs: 1W PA with 20% PAE, <4dB NF LNA, 4-bit phase shifter (<3dB loss)</li>
  - · G-band MMICs: 0.5W PA with 10% PAE, 6dB NF LNA
- 2. Develop low loss power combining and packaging technologies at 95GHz and 140GHz for future T/R modules
- 3. Address the integration of the MMICs for T/R modules



